

POLISHING PAD FOR CHEMICAL MECHANICAL POLISHING APPARATUS

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Polishing pad for chemical mechanical polishing apparatus

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Patent Details:

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Abstract (Basic): KR 2003037158 A

NOVELTY - A polishing pad for a chemical mechanical polishing (CMP) apparatus is provided to improve a removal rate and uniformity by forming a groove on a polishing pad surface.

DETAILED DESCRIPTION - Main grooves(3a) cross each other in a width direction and a length direction at regular intervals. Sub grooves are formed in division portions(3c) made by the formation of the main grooves in a width direction and a length direction, or form a predetermined angle with the main grooves. The width and depth of the sub grooves are smaller than those of the main grooves.

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